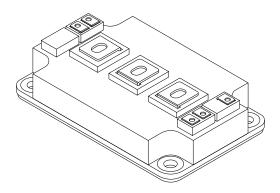
TTM Technologies

600V / 600A HALF BRIDGE PEM

4803

FEATURES:

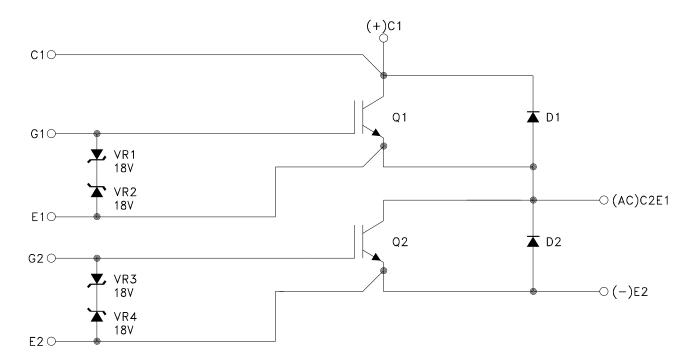
- · Half Bridge Configuration
- · 600V Rated Voltage
- 600A Continuous Output Current
- Internal Zener Clamps on Gates
- · Encapsulation Provides Near Hermetic Performance
- HI-REL Screening Available (Modified 38534)
- · Light Weight Domed ALSIC Baseplate
- · Robust Mechanical Design for Hi-Rel Applications
- Ultra-Low Inductance Internal Layout
- Withstands 96 Hours HAST and Thermal Cycling (-55°C to +125°C)
- · High Side Collector Sense Pin for De-Sat Detection



DESCRIPTION:

The MSK4803 is one of a family of plastic encapsulated modules (PEM) developed specifically for use in military, aerospace and other severe environment applications. The half bridge configuration and 600 volt/600 amp rating make it ideal for use in high current motor drive and inverter applications. The Aluminum Silicon Carbide (AlSiC) baseplate offers superior flatness and light weight; far better than the copper or copper alloys found in most high power plastic modules. The high thermal conductivity materials used to construct the MSK4803 allow high power outputs at elevated baseplate temperatures.

EQUIVALENT SCHEMATIC



TYPICAL APPLICATIONS

- Motor Drives
- Inverters

ABSOLUTE MAXIMUM RATINGS

(8)

VCE	Collector to Emitter Voltage600V	Tst	Storage Temperature Range955°C to +125°C
VGE	Gate to Emitter Voltage±20A	TJ	Junction Temperature150°C
lout	Current (Continuous)600A	Tc	Case Operating Temperature Range
IOUTP	Current Pulsed (1mS)1200A		MSK4803H55°C to +125°C
VCASE	Case Isolation Voltage2500V		MSK480340°C to +85°C

ELECTRICAL SPECIFICATIONS

Parameter (6)	Test Conditions	Group A	MSK4803H			MSK4803			Units
raiametei (b)	rest conditions	Subgroup	Min.	Тур.	Max.	Min.	Тур.	Max.	Units
		1	-	2.1	2.5	-	2.1	2.6	V
Collector-Emitter Saturation Voltage	Ic = 600A, VgE = 15V	2	-	2.5	2.9	-	-	-	V
		3	-	1.9	2.3	-	-	-	V
Collector-Emitter Leakage Current	Vce = 600V, Vge = 0V		-	0.2	10	-	0.2	10	uA
Collector-Efficier Leakage Current	VCE - 600V, VGE - 0V	2	-	0.1	1	-	-	-	mA
	Ic = 60mA, Vce = Vge	1	5.0	5.7	6.5	4.7	5.7	6.8	V
Gate Threshold Voltage		2	3.0	4.6	6.5	-	-	-	V
			4.0	6.5	8.5	-	-	-	V
		1	-	0.1	10	-	0.1	10	uA
Gate Leakage Current	$V_{CE} = 0V$, $V_{GE} = \pm 15V$	2	-	0.6	10	-	-	-	uA
			-	0.1	10	-	-	-	uA
	Ic = 600A	1	-	1.9	2.6	-	1.9	2.7	V
Diode Forward Voltage		2	-	1.9	2.6	-	-	-	V
			-	1.8	2.5	-	-	-	V
Total Gate Charge ①	V = 300V, Ic = 600A	4	-	3.9	5.2	-	3.9	5.5	uC
F() (i)	V = 300V, Ic = 600A, RG = 5Ω, V _{GE} = -7/+15V	4	-	25	-	-	25	-	mJ
E(on) ① —	V = 300V, Ic = 300A, RG = 5Ω, V _{GE} = -7/+15V	4	-	12	17	-	12	20	mJ
F/ 50 (A)	$V = 300V$, Ic = 600A, RG = 10Ω , $V_{GE} = -7/+15V$	4	-	73	-	-	73	-	mJ
E(off) ① —	$V = 300V$, Ic = 300A, RG = 10Ω , $V_{GE} = -7/+15V$	4	-	35	44	-	35	45	mJ
Diada Danasa Danasa Tima	I _E = 600, di/dt = 2100A/uS	4	-	130	-	-	130	-	nS
Diode Reverse Recovery Time 1 —	IE = 300, di/dt = 2100A/uS	4	-	100	-	-	100	-	nS
Diada Danasa Farasa (A	I _E = 600, di/dt = 2100A/uS	4	-	6.5	-	-	6.5	-	mJ
Diode Reverse Energy 1 —	I _E = 300, di/dt = 2100A/uS	4	-	3.0	5.0	-	3.0	5.3	mJ
T. 15 0	IGBT @ T _J = 125°C	-	-	0.07	0.09	-	0.07	0.9	°C/W
Thermal Resistance ① —	DIODE @ T _J = 125°C	-	-	0.09	0.10	-	0.09	0.10	°C/W

NOTES:

- Guaranteed by design but not tested. Typical parameters are representative of actual device performance but are for reference only.
- 2 Industrial grade devices shall be tested to subgroups 1 unless otherwise requested.
- ③ HI-REL grade devices ("H" suffix) shall be 100% tested to subgroups 1, 2 and sample tested to subgroup 3.
- 4 Subgroups 4 testing available upon request.
- ⑤ Subgroup 1, 4 TA = +25°C
 - 2 TA = $+125^{\circ}$ C
 - 3 TA = -55° C
- 6 All specifications apply to both the upper and lower sections of the half bridge.
- 7 VGE=15V unless otherwise specified.
- (8) Continuous operation at or above absolute maximum ratings may adversly effect the device performance and/or life cycle
- (9) Internal solder reflow temperature is 180°C, do not exceed.

APPLICATION NOTES

THERMAL CALCULATIONS

Power dissipation and maximum allowable temperature rise involve many variables working together. Collector current, PWM duty cycle and switching frequency all factor into power dissipation. DC losses or "ON-TIME" losses are simply VCE(SAT) x Collector Current x PWM duty cycle. For the MSK4803, VCE(SAT) = 2.5V max., and at 600 amps and a PWM duty cycle of 30%, DC losses equal 450 watts. Switching losses vary proportionally with switching frequency. The MSK4803 typical switching losses at VCE = 300V and ICE = 600A are about 98mJ, which is simply the sum of the turn-on switching loss and the turn-off switching loss. Multiplying the switching frequency times the switching losses will result in a power dissipation number for switching. The MSK4803, at 5KHz, will exhibit switching power dissipation of 490 watts. The total losses are the sum of DC losses plus switching losses, or in this case, 940 watts total. 940 watts x 0.09°C/W thermal resistance equals 85 degrees of temperature rise between the case and the junction. Subtracting 85°C from the maximum junction temperature of 150°C equals 65°C maximum case temperature for this example.

VCE(SAT) x IC x PWM duty cycle = 2.5V x 600 amps x 30% = 450 watts DC losses

Turn-on switching loss + Turn-off switching loss = Total switching losses = 2.5 + 73 = 98mJ

Total switching loss x PWM frequency = Total switching power dissipation = 98mJ x 5KHz = 490 watts

Total power dissipation = DC losses + switching losses = 450 + 490 = 940 watts

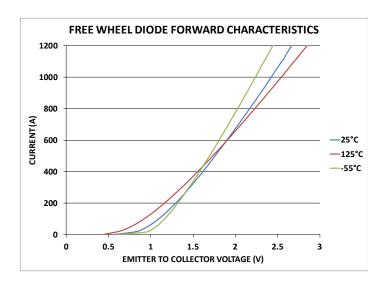
Junction temperature rise above case = Total power dissipation x thermal resistance

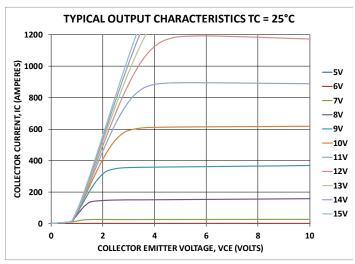
940 watts x 0.09°C/W = 84.6°C temperature rise above case

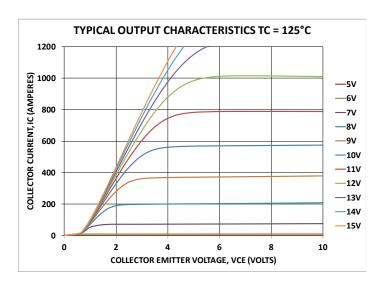
Maximum junction temperature - junction temperature rise = maximum baseplate temperature

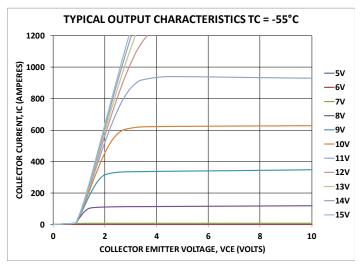
150°C - 85°C = 65°C

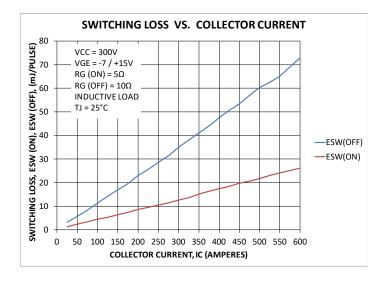
TYPICAL PERFORMANCE CURVES

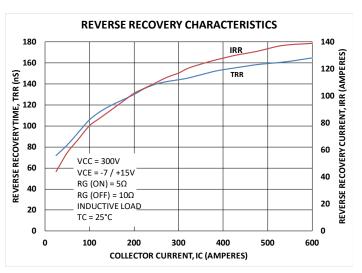












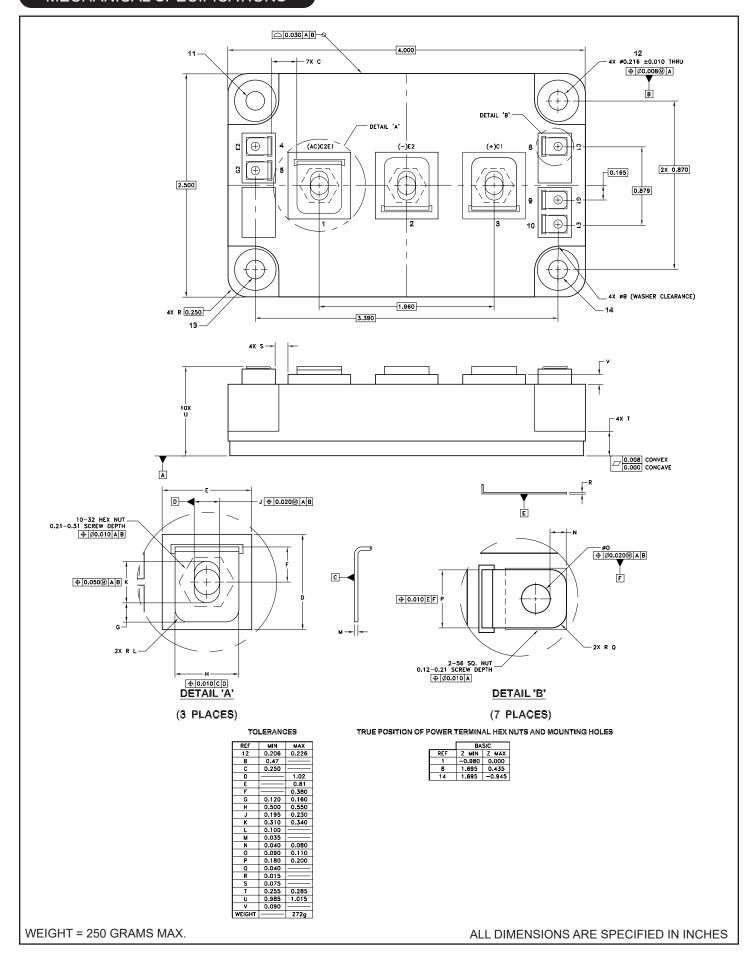
SCREENING CHART

OPERATION	INDUSTRIAL	H SUFFIX		
QUALIFICATION (MODIFIED)	NO	YES		
ELEMENT EVALUATION	NO	YES		
CLEAN ROOM PROCESSING	YES	YES		
NON DESTRUCT BOND PULL SAMPLE	YES	YES		
CERTIFIED OPERATORS	NO	YES		
MIL LINE PROCESSING	YES	YES		
MAX REWORK SPECIFIED	NO	YES		
ENCAPSULANT	GEL COAT	GEL COAT		
PRE-CAP VISUAL	YES - INDUSTRIAL	YES - CLASS H		
TEMP CYCLE (-55°C TO +125°C)	NO	YES		
BURN-IN	NO	YES - 160 HOURS		
ELECTRICAL TESTING	YES - 25°C	YES - FULL TEMP		
EXTERNAL VISUAL	YES - SAMPLE	YES		
XRAY	NO	NO		
PIN FINISH	NI	NI		

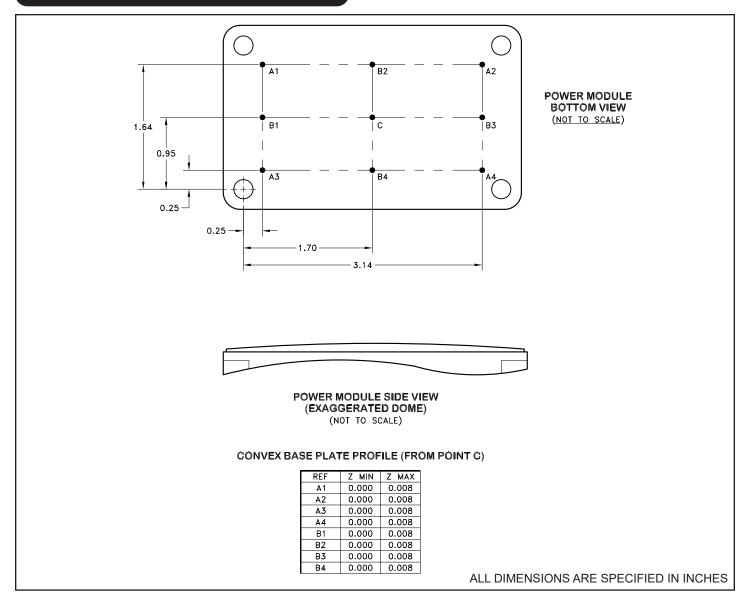
NOTE: ADDITIONAL SCREENING IS AVAILABLE SUCH AS XRAY, CSAM, MECHANICAL SHOCK, ETC. CONTACT FACTORY FOR QUAL STATUS.

5

MECHANICAL SPECIFICATIONS



MECHANICAL SPECIFICATIONS CONT'D





THE ABOVE EXAMPLE IS A HI-REL SCREENED MODULE.

REVISION HISTORY

REV	STATUS	DATE	DESCRIPTION
В	Released	04/14	Add form number. Update electrical specifications and performance curves for new generation IGBT and diode
С	Released	09/14	Correct outline and add labels
D	Released	08/17	Update ICES subgroup 2 limit
E	Released	07/20	Change maximum limit of Gate Threshold Voltage for subgroup 2 from 5.6V to 6.5V

ANAREN, MSK Products www.anaren.com/msk